

General Description

The WSR4N65F is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The WSR7N65F meet the RoHS and Green Product requirement , 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

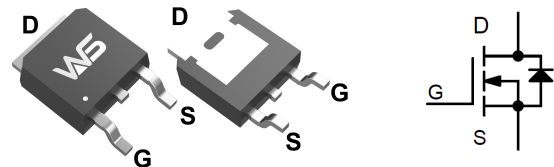
Product Summary

BV_{DSS}	R_{DSON}	I_D
650V	2.6Ω	4A

Applications

- AC/DC Power Conversion in Switched Mode Power Supplies (SMPS).
- Uninterruptible Power Supply(UPS)
- Adapter.

TO-252 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	650	V
V_{GS}	Gate-Source Voltage	±30	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^{1,5}$	4	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^{1,5}$	2.5	A
I_{DM}	Pulsed Drain Current ^{1,2,5}	16	A
EAS	Single Pulse Avalanche Energy ¹	128	mJ
P_D	Total Power Dissipation ^{1,5}	77	W
T_{STG}	Storage Temperature Range	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	62.5	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	1.62	°C/W

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	650	---	---	V
ΔBV _{DSS} /ΔT _J	BVDSS Temperature Coefficient	Reference to 25°C, I _D =250uA	---	0.6	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =3.5A	---	2.6	3.0	Ω
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	2.0	3.0	4.0	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	-4.57	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =650V, V _{GS} =0V, T _J =25°C	---	---	1	uA
		V _{DS} =520V, V _{GS} =0V, T _J =55°C	---	---	10	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±30V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =40V, I _D =3.5A	---	5	---	S
Q _g	Total Gate Charge (10V)	V _{DS} =520V, V _{GS} =10V, I _D =7A	---	10.2	---	nC
Q _{gs}	Gate-Source Charge		---	2.3	---	
Q _{gd}	Gate-Drain Charge		---	2.1	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =300V, V _{GS} =10V, R _G =25Ω, I _D =10A.	---	15.5	---	ns
T _r	Rise Time		---	13	---	
T _{d(off)}	Turn-Off Delay Time		---	40	---	
T _f	Fall Time		---	16	---	
C _{iss}	Input Capacitance	V _{DS} =25V, V _{GS} =0V, f=1MHz	---	550	---	pF
C _{oss}	Output Capacitance		---	46	---	
C _{rss}	Reverse Transfer Capacitance		---	2.3	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,2,5}	V _G =V _D =0V, Force Current	---	---	4	A
I _{SM}	Pulsed Source Current ^{1,2}		---	---	16	A
V _{SD}	Diode Forward Voltage ¹	V _{GS} =0V, I _S =7A, T _J =25°C	---	---	1.4	V
t _{rr}	Reverse Recovery Time	I _F =7A, dI/dt=40A/μs, T _J =25°C	---	454	---	nS
Q _{rr}	Reverse Recovery Charge		---	2076	---	nC

Notes:

Note 1 : limited by maximum junction temperature.

Note 2 : Bond wire current limit.

Note 3 : V_{DS}=520V, I_D=4A.

Note 4 : I_D=0.5A, V_{DD}=50V, T_J=25°C.

Note 5 : Repetitive Rating : Pulse width limited by maximum junction temperature.

Typical Characteristics

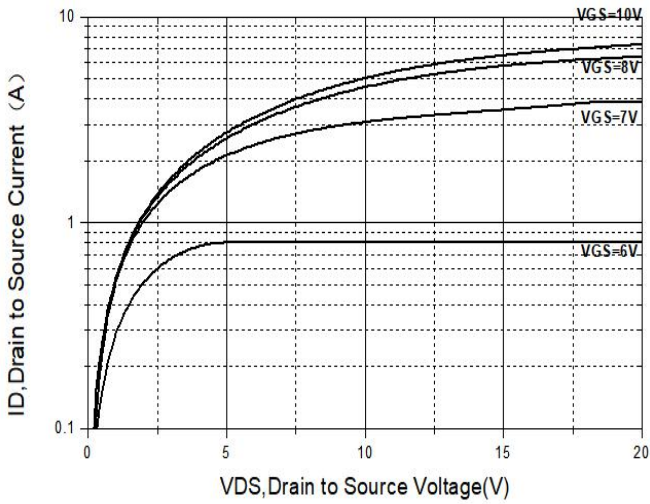


Figure 1 Output Characteristics

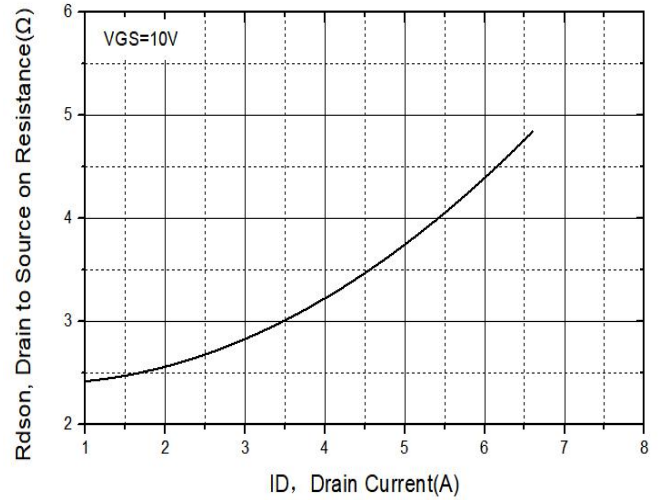


Figure 3 $R_{DS(on)}$ - I_D Characteristics

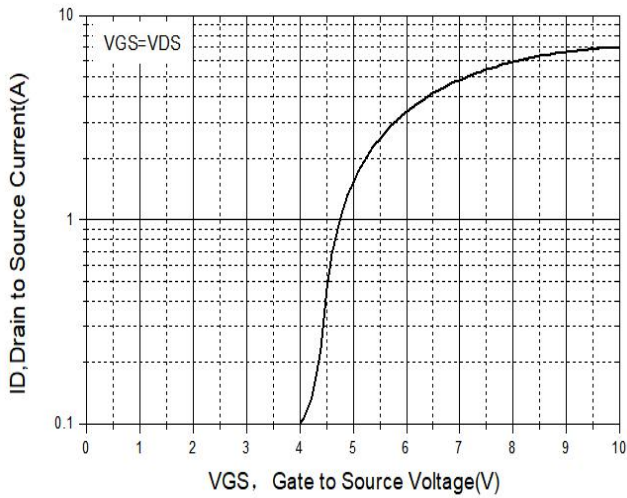


Figure 2 Transfer Characteristics

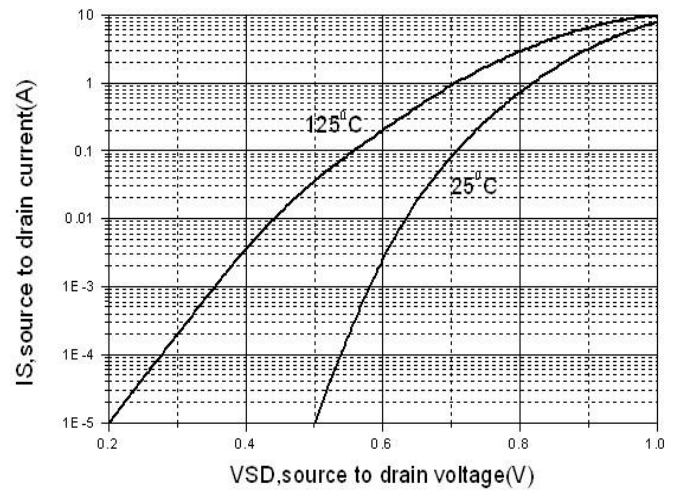


Figure 4 Body diode Characteristics

Typical Characteristics

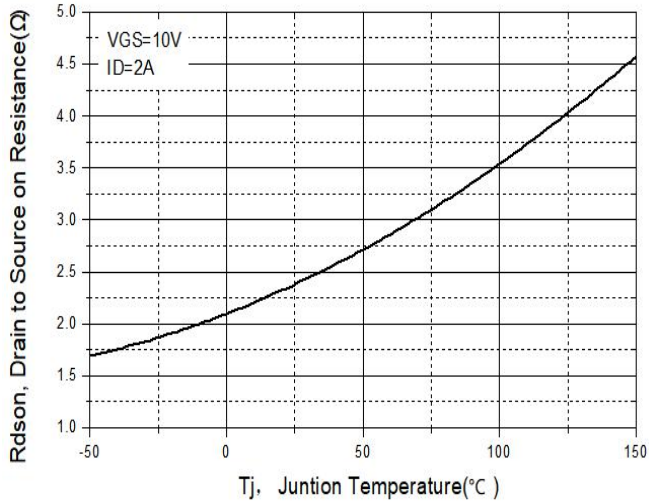


Figure 5 Rdson- Tj Relation

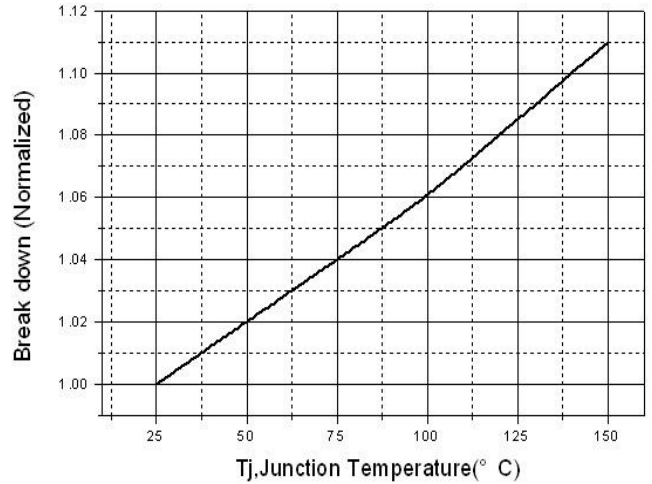


Figure 6 BVDSS vs Junction Temperature

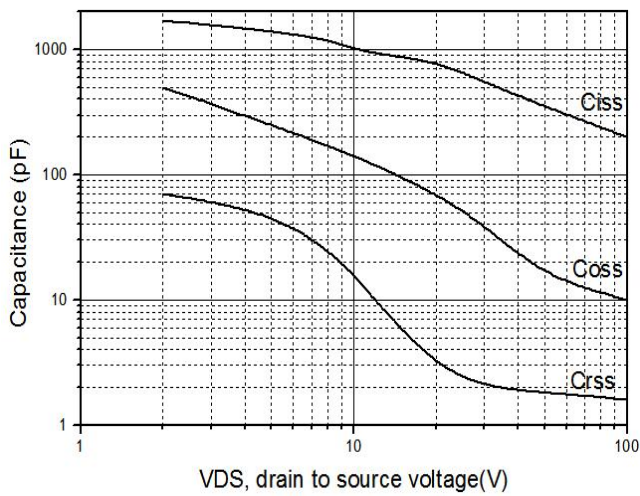


Figure 7 Capacitance vs Vds

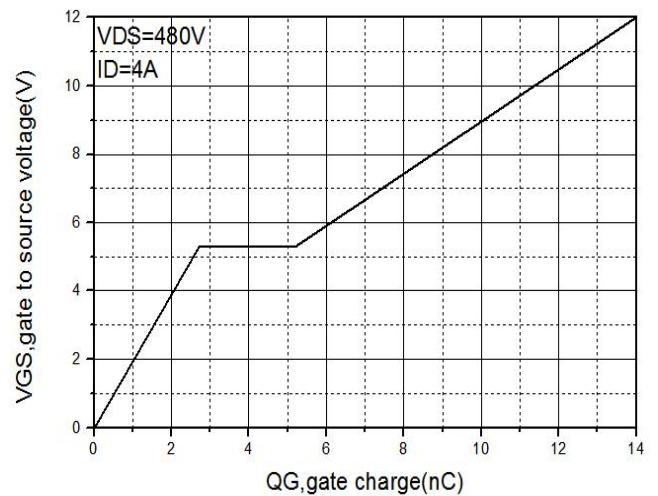


Figure 8 VGS vs QG Characteristics

Typical Characteristics

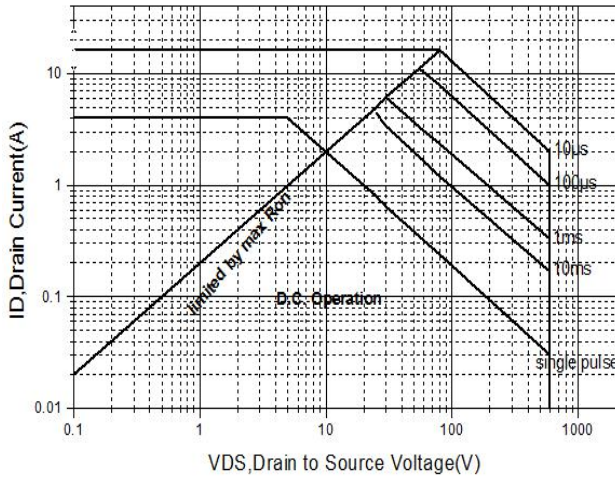


Figure 9 Safe Operation Area

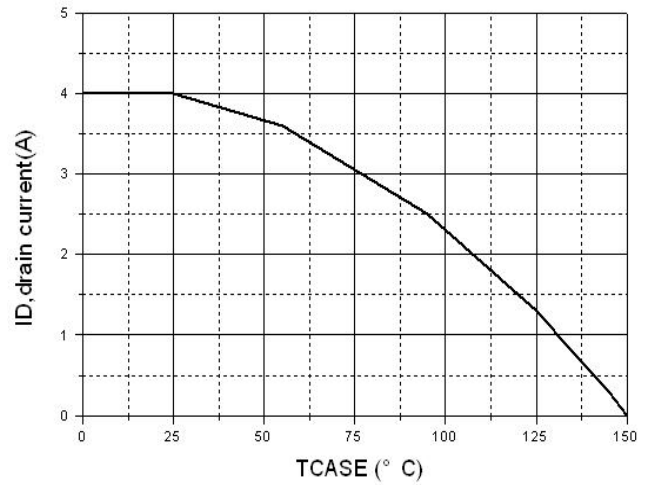


Figure 10 Maximum current attenuation

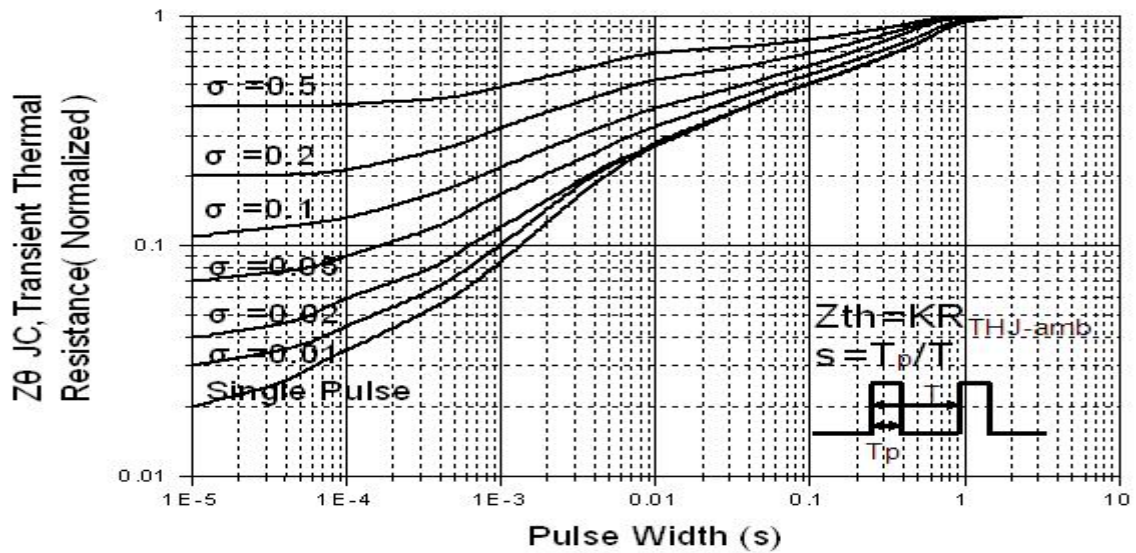


Figure 11 Normalized Maximum Transient Thermal Impedance

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